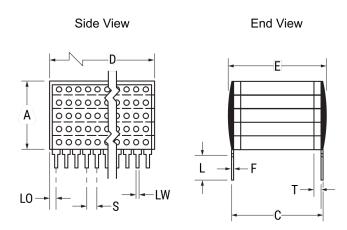




KPS LDD Comm SMPS, Ceramic, 4.7 uF, 10%, 500 VDC, X7R, N/A



Click here for the 3D model.

| Dimensions | |
|------------|---------------------|
| D | 25.715mm +/-1.585mm |
| L | 6.35mm MIN |
| Т | 1.397mm MAX |
| S | 2.54mm TYP |
| F | 0.254mm +/-0.051mm |
| А | 6.096mm MAX |
| С | 11.43mm +/-0.635mm |
| E | 12.7mm NOM |
| G | 1.4mm +/-0.25mm |
| LO | 1.586mm MAX |
| LW | 0.508mm +/-0.051mm |

| Packaging Specifications | |
|--------------------------|-------------|
| Packaging | Waffle, Box |
| Packaging Quantity | 28 |

| General Informa | tion | |
|----------------------------|--|--|
| Series | KPS LDD Comm SMPS | |
| Style | Leaded Stacked Chip | |
| Description | Low ESR, High Current Stacked Ceramic Chips | |
| Features | Low ESR, High Current, High Performance | |
| RoHS | No | |
| Prop 65 | ▲ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov. | |
| Termination | 60/40 Solder Coated | |
| Lead | Wire Leads | |
| Failure Rate | N/A | |
| Testing and Reliability | Commercial | |
| AEC-Q200 | No | |
| Notes | Note: Number of chips in stack depends on design. Number of Chips in this stack = 2. Note: Lead alignment within pin rows shall be within ±.0.13 mm. | |

| Specifications | |
|---------------------------------|---------------------|
| Capacitance | 4.7 uF |
| Capacitance Tolerance | 10% |
| Voltage DC | 500 VDC |
| Dielectric Withstanding Voltage | 750 VDC |
| Temperature Range | -55/+125°C |
| Temperature Coefficient | X7R |
| Dissipation Factor | 2.5% 1 kHz 25C |
| Aging Rate | 3% Loss/Decade Hour |
| Insulation Resistance | 21.3 GOhms |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.